

EPOXY RESIN COMPOSITION

Abstract

According to the invention there is provided an epoxy resin composition used for sealing of semiconductor devices, comprising:

- (A) an epoxy resin of the formula II,
- (B) an epoxy resin curing agent,
- (C) a mixture of inorganic aluminum oxide and silicon oxide constituting 69.5-95% by weight of the total epoxy resin composition,
- (D) a curing accelerator